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**ATTORNEYS AT LAW**
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**SUITE 205**
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Information Disclosure Statement
Form PTO-1449 and Cited Reference(s)



January 21, 2004
YOR920030175US1
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FORM PTO-1449 (MODIFIED)

LIST OF PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT

Applicant(s): Allen et al.
Docket No.: YOR920030175US1
Serial No.: 10/661,041
Filing Date: September 12, 2003
Group: 2811

## U.S. PATENT DOCUMENTS

| EXAMINER INITIAL | DOCUMENT NO. | DATE | NAME | CLASS/SUBCLASS | FILING DATE IF APPROPRIATE |
|---|---|---|---|---|---|
| _____ | 6,316,167 | 11/13/01 | Angelopoulos et al. | 430/313 | |

## FOREIGN PATENT DOCUMENTS

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## OTHER DOCUMENTS

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|---|---|---|
| _____ | | Chun et al., "Contact Hole Size Reducing Methods by Using Water-Soluble Organic Over-Coating Material (WASOOM) as a Barrier Layer Toward 0.15 um Contact Hole; Resist Flow Technique I," Proc. SPIE, Vol. 3999, pgs. 620-626 (2000). |
| _____ | | Chung et al., "A Novel Resist Material for sub-100 nm Contact Hole Pattern," Proc. SPIE, Vol. 3999, pgs. 305-312 (2000). |
| _____ | | DellaGuardia et al., "193 Lithography and RELACS™ Processing for BEOL Lithography," Proc. SPIE, Vol. 4346, pgs. 1029-1040 (2001). |
| _____ | | Lucas et al., "193 nm Contact Photoresist Reflow Feasibility Study," Proc. SPIE, Vol. 4345, pgs. 725-736 (2001). |
| _____ | | Satou et al., "Sub-0.10 μm Hole Fabrication Using Bilayer Silylation Process for 193 nm Lithography," Jpn. J. Appl. Phys. 1, Vol. 38, Part 1, No. 12B, pgs 7008-7012 (December 1999). |

Examiner Date Considered

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| CA | | Chun et al., "Contact Hole Size Reducing Methods by Using Water-Soluble Organic Over-Coating Material (WASOOM) as a Barrier Layer Toward 0.15 um Contact Hole; Resist Flow Technique I," Proc. SPIE, Vol. 3999, pgs. 620-626 (2000). |
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Examiner

9-06-05
Date Considered

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Ryan, Mason & Lewis, LLP
ATTORNEYS AT LAW
1300 POST ROAD
SUITE 205
FAIRFIELD, CT 06824

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February 23, 2005
YOR920030175US1
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**FORM PTO-1449 (MODIFIED)**

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| _____ | 5,753,418 | 05/19/98 | Tsai et al. | 430/313 | |
| _____ | 6,009,888 | 01/04/00 | Ye et al. | 134/1.3 | |
| _____ | 6,316,167 | 11/13/01 | Angelopoulos et al. | 430/313 | |
| _____ | 6,387,798 | 05/14/02 | Loke et al. | 438/623 | |
| _____ | 6,514,867 | 02/04/03 | Hui et al. | 438/713 | |

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| _____ | EP 0 236 220 A1 | 13/04/88 | Europe | | | |

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|---|---|---|
| _____ | | Celii et al., "Process Characterization for Tapered Contact Etch," J. Vac. Sci. Technol. B 19(5), American Vacuum Society, Pgs. 1845-1851 (Sept/Oct 2001). |
| _____ | | Mahorowala et al., "Tunable Anti-Reflective Coatings with Built-In Hard Mask Properties Facilitating Thin Resist Processing," Proceedings of the SPIE, Vol. 4343, Pgs. 306-316 (2001). |

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Examiner

6-16-05
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